# XP02401 (XP2401)

# Silicon PNP epitaxial planar type

### For general amplification

#### ■ Features

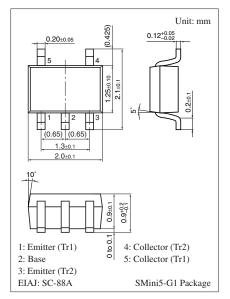
- Two elements incorporated into one package (Base-coupled transistors)
- Reduction of the mounting area and assembly cost by one half

#### ■ Basic Part Number

• 2SB0709A (2SB709A) × 2

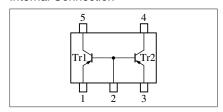
## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-60	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-50	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	-7	V	
Collector current	$I_C$	-100	mA	
Peak collector current	$I_{CP}$	-200	mA	
Total power dissipation	$P_{T}$	150	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	



Marking Symbol: 7R

#### Internal Connection



## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

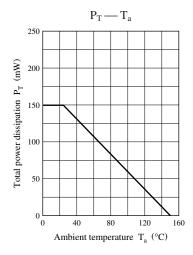
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = -10 \mu A, I_E = 0$	-60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = -2 \text{ mA}, I_B = 0$	-50			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \ \mu A, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -20 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = -10 \text{ V}, I_B = 0$			-100	μΑ
Forward current transfer ratio	$h_{FE}$	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	160		460	_
h <sub>FE</sub> ratio *	h <sub>FE(Small/</sub>	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	0.50	0.99		_
	Large)					
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$		- 0.3	- 0.5	V
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2.7		pF
(Common base, input open circuited)						

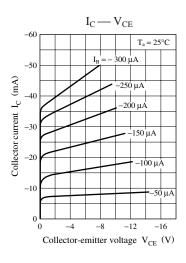
 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7030 \ measuring \ methods \ for \ transistors.$ 

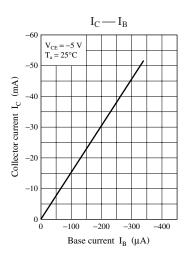
2. \*: Ratio between 2 elements

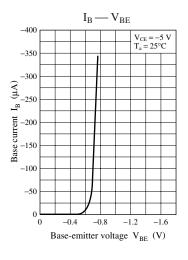
Note) The part number in the parenthesis shows conventional part number.

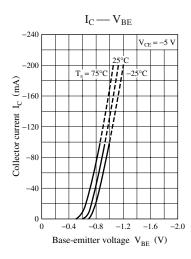
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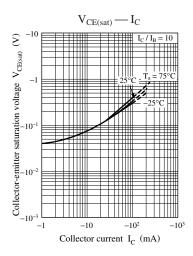


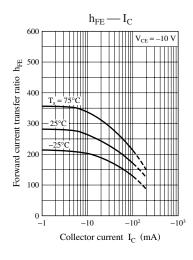


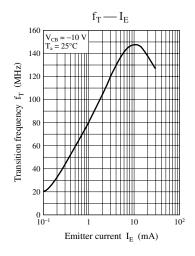


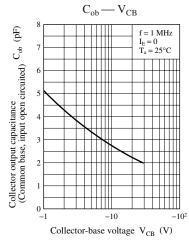


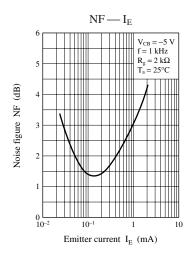


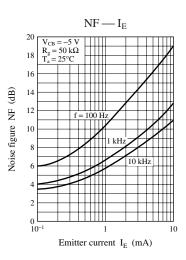


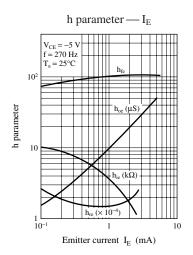


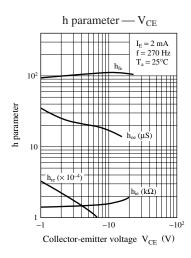












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